

ABSTRACT OF THE DISCLOSURE

This invention provides a mounting method for reliably connecting mounting components electrically. Specifically, an anisotropically conductive adhesive can be composed of crushable microcapsules and a second liquid in which the microcapsules are dispersed. Each microcapsule encloses a first liquid and a conductive particle. The first liquid can react with the second liquid at normal temperatures to cure the second liquid. This anisotropically conductive adhesive can be applied on a flexible printed circuit (FPC). Then, a drive IC is mounted and pressed on the FPC to crush the microcapsules between electrode pads provided on the drive IC and electrode pads provided on the FPC, thereby bonding the electrode pads. Subsequently, the anisotropically conductive adhesive is heated to plasticize a capsule wall of each microcapsule, thereby bonding the drive IC and the FPC.